

## CLAIMS

*ruban* 1. An integrated circuit die including first and second sets of conductive pads for enabling external connections to be made to the integrated circuit, there being at least a first predetermined center-to-center spacing between each pad of the first set and the adjacent pad or pads of the first set, and at least a second predetermined center-to-center spacing, less than said first spacing, between each pad of the second set and the adjacent pad or pads of the first and second sets, and a passivation layer exposing only pads of the first set, or exposing pads of the first and second sets.

2. A die as claimed in claim 1 wherein the pads of the first set are larger in area than the pads of the second set.

3. A die as claimed in claim 2 wherein the area of each pad of the first set and the first predetermined center-to-center spacing are suitable for flip-chip assembly of the die, and the area of each pad of the second set and the second predetermined center-to-center spacing are suitable for wire bond assembly of the die.

4. A die as claimed in claim 1 wherein the pads of the first and second sets are disposed in line adjacent one or more edges of the die.

5. A die as claimed in claim 1 wherein the pads of the first set are disposed in two lines adjacent one or more edges of the die, the pads of the first set in one of the two lines being disposed in staggered relationship with respect to the pads of the first set in the other of the two lines.

6. A die as claimed in claim 5 wherein the pads of the second set are disposed in one of the two lines.

7. A die as claimed in any preceding claim wherein the first set of pads is connected to one set of connection points in the integrated circuit, and the second set of pads is connected to another set of connection points in the integrated circuit.

*ruban* 8. An integrated circuit die, comprising:  
a first set of conductive pads having a first minimum distance therebetween; and  
a second set of conductive pads having a second minimum distance therebetween,  
and between a pad of the second set and a neighboring pad of the first set,  
wherein the die is adapted for selective use as one of a flip-chip assembly and a wire bond assembly.

1 9. A die as recited in claim 8, further comprising a first passivation layer for use  
2 of the die as a flip-chip assembly.

*sub 3* 10. A die as recited in claim 8, further comprising a second passivation layer for  
2 use of the die as a wire bond assembly.

*add 4*

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